

**BRBSS84Q**  
Rev.A Mar.-2023



SOT-23 P  
P-CHANNEL MOSFET in a SOT-23 Plastic Package.

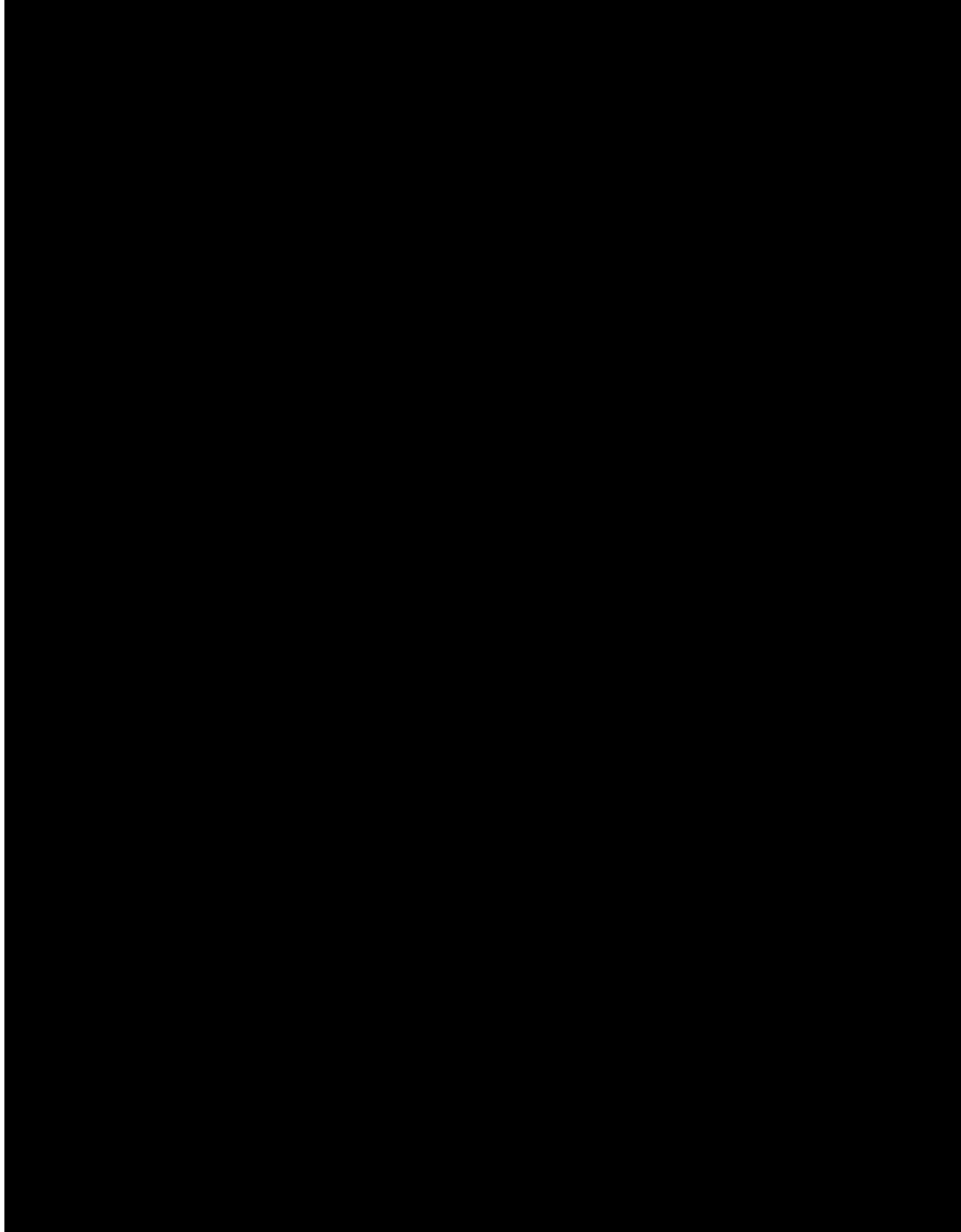
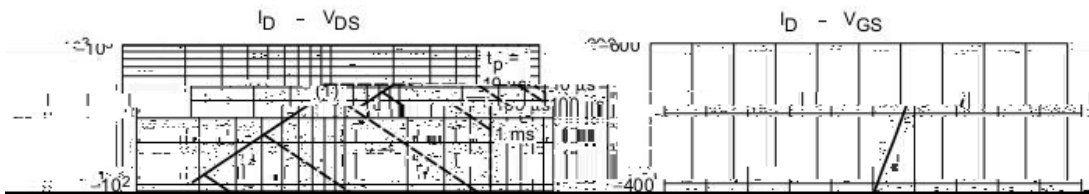
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Low threshold voltage, Direct interface to C-MOS, TTL etc, High-speed switching,ESD Improved

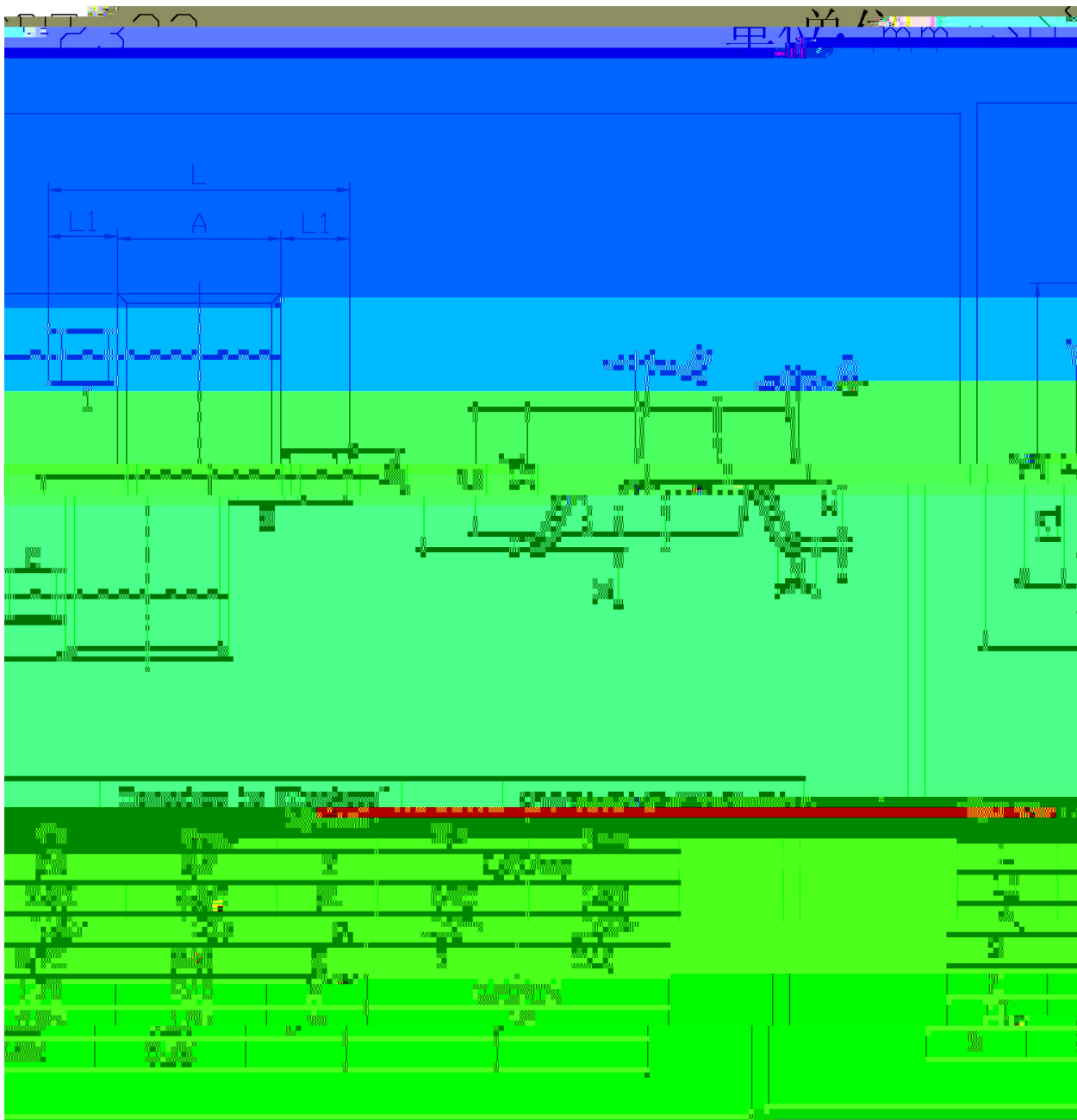
Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DSS}$	-50	V
Drain Current – Continuous	$I_D$	-130	mA
Peak Drain Current	$I_{DM}$	-520	mA
Gate-Source Voltage	$V_{GSS}$	$\pm 20$	V
Thermal Resistance, Junction-to-Ambient	$R_{JA}$	500	/W
Storage Temperature Range	$T_{stg}$	-65 to 150	
Junction Temperature Range	$T_j$	150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain–Source Breakdown Voltage	$V_{DSS}$	$V_{GS}=0V$ $I_D=-10\mu A$	-50			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ $I_D=-250\mu A$	-0.8		-2.0	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{GS}=0V$ $V_{DS}=-40V$			-100	nA
		$V_{GS}=0V$ $V_{DS}$				

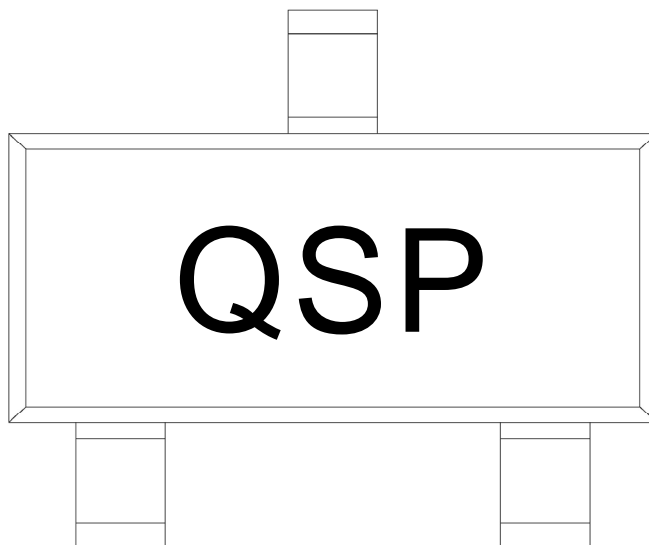
/ Electrical Characteristic Curve



/ Package Dimensions



/ Marking Instructions



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SP

Note:

Q: Automobile halogen-free product Code

SP: Product Type.

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)


Note:

- |   |           |              |   |
|---|-----------|--------------|---|
| 1 | 150 ~ 200 | 60 ~ 120sec; | 1.Preheating:150~200 , Time:60~120sec.    |
| 2 | 255..5    | 5..0.5sec;   | 2.Peak Temp.:255..5 , Duration:5..0.5sec. |
| 3 | 2 ~ 10    | /sec.        | 3.Cooling Speed: 2~10 /sec.               |

/ Resistance to Soldering Heat Test Conditions

260..5	10..1 sec.	Temp.:260..5	Time:10..1 sec
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/ Packaging SPEC.

/ REEL

Package Type